

Appl. No. : 09/389,720
Filed : September 3, 1999

REMARKS

This is responsive to the Examiner's Office Action mailed February 4, 2003. Applicant has hereby amended Claims 20 and 26. Claims 20-24, 26, 29 and 30 are currently pending in this application.

A summary document is included herein above with the status of all claims and the text of all pending claims. The specific changes to the amended claims are shown by ~~strike through for any deletions~~ and underlining for any insertions.

SPECIFICATION

Applicant has amended the specification to bring it in compliance with the amendment to Claim 26. Specifically, "polymide" has been replaced with --polyimide--.

CLAIMS

Objections

The Examiner objected to Claim 26 and stated that there appeared to be a typographical error in the word "polymide".

As set forth in the response filed November 1, 2002, Applicant has noted that in the art different spellings are used for "polymide," for example, "polyimide." Thus, the skilled artisan would recognize that the word "polymide" encompasses all these spelling variations and modifications.

In this case, Applicant has amended Claim 26 to overcome the Examiner's objection. This amendment does not narrow the scope of the claim.

Rejections

The Examiner rejected Claims 20-24, 29 and 30 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 5,661,086 to Nakashima et al. (hereafter "Nakashima") and Claims 20-24 and 26 under 35 U.S.C. § 102(b) as being anticipated by U.S. Patent No. 3,942,245 to Jackson et al. (hereafter "Jackson").

Applicant respectfully traverses these rejections and the Examiner's characterization of the cited references. In this case, Applicant has amended Claim 20 to more particularly define embodiments of the invention.

Independent Claim 20 is directed to an assembly and recites, among other things, that the substrate units are electrically interfaced with the dies, the carrier is in mechanical

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communication with the first surface of the film and the dies are attached to a second surface of the film with the second surface being opposed to the first surface. None of the cited references disclose, teach or suggest an assembly as set forth in Applicant's Claim 20.

Nakashima teaches a metal substrate (12 or 12') characterized by the Examiner as the "film". It is not clear to Applicant what the Examiner considers to be the "carrier", but it appears that the Examiner considers the circuit substrate (17) to be the carrier. In this case, the die (14 or 14') and the carrier (17) are connected to the same surface of the film (12 or 12'), that is, the lower surface in FIGS. 1 and 4. Thus, Nakashima cannot possibly anticipate Applicant's Claim 20.

Jackson teaches a polyimide film (11) and a metal sheet (12) characterized by the Examiner as the "carrier". As clearly shown in FIG. 3, the semiconductor device (20) as taught by Nakashima does not connect to any surface of the film (11), but instead connects to the carrier (12) which is connected to the film (11). Even if it is assumed that the device (20) connects to the surface of the film (11), it is clear from FIG. 3 that both the device (20) and carrier (12) would connect to the same surface of the film (11), that is, the upper surface in FIG. 3. Thus, Jackson cannot possibly anticipate Applicant's Claim 20.

Claims 21-24, 26, 29 and 30 depend from Claim 20, and each recites a unique combination of features not taught by the prior art. Therefore, Applicant submits that Claims 20-24, 26, 29 and 30 are in condition for allowance.

INFORMATION DISCLOSURE STATEMENT

Applicant is submitting herewith a Supplemental Information Disclosure Statement. The Examiner's consideration of this Information Disclosure Statement is respectfully requested.

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CONCLUSION

In view of the foregoing, the present application is believed to be in condition for allowance, and such allowance is respectfully requested. If further issues remain to be resolved, the Examiner is cordially invited to contact the undersigned such that any remaining issues may be promptly resolved. Also, please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Respectfully submitted,

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Dated: 4/2/03

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